

CLAIMS

1. An electronic module (2) configured for inlay
into a cavity of a card body (3) and for mounting of a
selected radiofrequency integrated circuit chip (6),
5 wherein said module (2) comprises

- an insulating support layer (12),

- an radiofrequency circuit on said insulating
support, wherein said circuit comprises plates of an
adjustable capacitor and/or an antenna helix (5) with
10 adjustable inductance,

- at least one element (17) for adjusting a
tuning frequency of the radiofrequency circuit,

characterised in that:

- said plates (13A-13H) comprising a first plate
15 (13A) and/or said antenna helix (5) extend on said
support layer (12) of the module (2) and in that said
adjustment element (17, 38) connects an intermediate
point (16B) of the antenna helix (5) to reduce the
available inductance and/or splits or connects the
20 plates to adjust the capacitance, wherein the module
(2) has a main face and a second face; and

- said adjustment is configurable to equal or
compensate for a variation in internal capacitance (cc)
and/or internal inductance of the selected
25 radiofrequency integrated circuit chip (6).

2. The module (2) according to claim 1, characterised in that the main face (12A) has an area less than or equal to 375 mm².

3. Device according to any of the above claims,
5 characterised in that said adjustment is configurable for a variation in internal capacitance (cc) greater than 5 μ F.

4. The module (2) according to any one of the above claims, characterised in that the module (2)
10 comprises at least two second conductive plates (13B, 13C) on said second face (12B) arranged opposite at least said first plate (13A) so as to form said adjustable capacitor (14), wherein said second plates (13B, 13C) are connected electrically by at least one
15 electrical connection (17).

5. The module (2) according to the above claim, characterised in that said electrical connection (17) between said two second plates (13B, 13C) is a bonded wire.

20 6. The module (2) according to claim 5, characterised in that said electrical connection (17) between said two second plates (13A, 13B) is a conductive printing or an electrically conductive deposit.

25 7. The module (2) according to claim 5, characterised in that said electrical connection (17)

is pre-wired by metallization of the insulating layer and has a de-short-circuiting break mark.

8. The module (2) according to any of the above claims, characterised in that the antenna helix (5) comprises several turns (11) and features connection ends or terminals (15A, 16A) emerging on the second face (12B).